

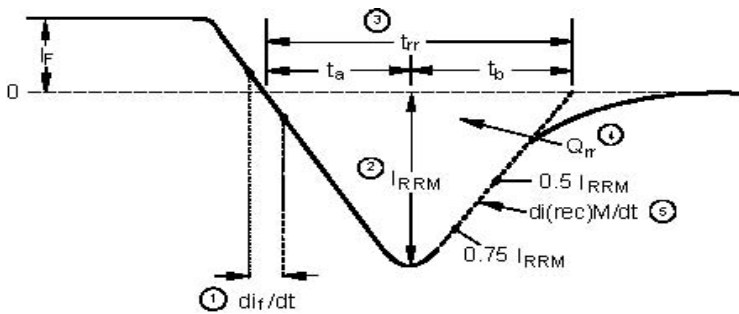


PRELIMINARY SPECIFICATION №140. **SUPERFAST DIODE KD-0560 SF .**

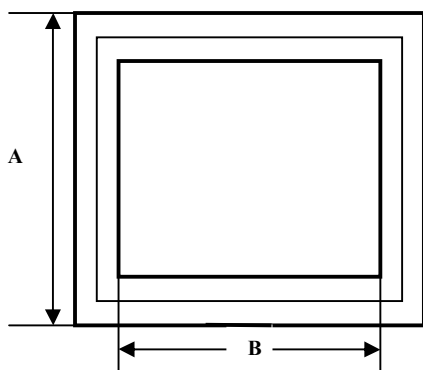
 VSP MIKRON		5A/600V. Die Size-75*76mil.		
Electrical Characteristics	Symbol	Unit	Spec. limit	Die Sort
Breakdown Voltage @ $I_R=0,10\text{mA}$	V_B	V	600	620
Average Rectified Forward Current	$I_{F(AV)}$	A	5,0	-
DC Forward Voltage @ $25^\circ\text{C}, I_F=5,0\text{A}$	V_F	V	2,50	2,45
Maximum Reverse Current @ $25^\circ\text{C}, V_R=600\text{V}$ @ $125^\circ\text{C}, V_R=600\text{V}$	I_R	MA	0,010 0,500	0,009 0,450
Reverse Recovery Time, $I_F=1\text{A}, V_R=30\text{V}, di_F/dt=100\text{A}/\mu\text{S}.$	t_{rr}	nS	30	28
Operating Junction Temperature	T_J	$^\circ\text{C}$	175	



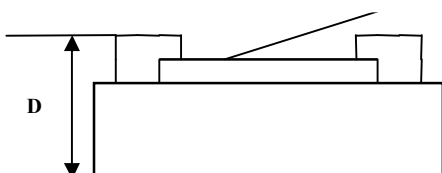
1. di_F/dt - Rate of change of current through zero crossing
2. I_{RRM} - Peak reverse recovery current
3. t_{rr} - Reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through $0.75 I_{RRM}$ and $0.50 I_{RRM}$ extrapolated to zero current
4. Q_{rr} - Area under curve defined by t_{rr} and I_{RRM}
5. $di(\text{rec})M/dt$ - Peak rate of change of current during t_b portion of t_{rr}

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

DIM	ITEM	μm
A_X A_Y	Die Size	1900 1940
B_X B_Y	Top Metal Size	1160 1200
D	Thickness	350max.
Scribe line Width		60



Top Metal



Top metal: Al – for Wire Bonding.

Backside metal: Ti-Ni-Ag – for Soldering.

www.vsp-mikron.com